RELIABILITY REPORT
FOR
MAX8663ETL+
PLASTIC ENCAPSULATED DEVICES

April 6, 2010

MAXIM INTEGRATED PRODUCTS
120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Don Lipps
Quality Assurance
Manager, Reliability Engineering
Conclusion

The MAX8663ETL+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX8662/MAX8663 power-management ICs (PMICs) are efficient, compact devices suitable for smart cellular phones, PDAs, Internet appliances, and other portable devices. They integrate two synchronous buck regulators, a boost regulator driving two to seven white LEDs, four low-dropout linear regulators (LDOs), and a linear charger for a single-cell Li-ion (Li+) battery. Maxim's Smart Power Selector (SPS) safely distributes power between an external power source (AC adapter, auto adapter, or USB source), battery, and the system load. When system load peaks exceed the external source capability, the battery supplies supplemental current. When system load requirements are small, residual power from the external power source charges the battery. A thermal-limiting circuit limits battery-charge rate and external power-source current to prevent overheating. The PMIC also allows the system to operate with no battery or a discharged battery. The MAX8662 is available in a 6mm x 6mm, 48-pin thin QFN package, while the MAX8663, without the LED driver, is available in a 5mm x 5mm, 40-pin thin QFN package.
II. Manufacturing Information

A. Description/Function: Power-Management ICs for Single-Cell, Li+ Battery-Operated Devices
B. Process: S45
C. Number of Device Transistors: 33204
D. Fabrication Location: California, Texas or Japan
E. Assembly Location: China, Thailand
F. Date of Initial Production: February 15, 2007

III. Packaging Information

A. Package Type: 40-pin TQFN 5x5
B. Lead Frame: Copper
C. Lead Finish: 100% matte Tin
D. Die Attach: Conductive
E. Bondwire: Au (2 mil dia.)
F. Mold Material: Epoxy with silica filler
G. Assembly Diagram: #05-9000-2260
H. Flammability Rating: Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C: Level 1
J. Single Layer Theta Ja: 45°C/W
K. Single Layer Theta Jc: 1.7°C/W
L. Multi Layer Theta Ja: 28°C/W
M. Multi Layer Theta Jc: 1.7°C/W

IV. Die Information

A. Dimensions: 140 X 140 mils
B. Passivation: Si₃N₄/SiO₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect: Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization: None
E. Minimum Metal Width: Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing: Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions: 5 mil. Sq.
H. Isolation Dielectric: SiO₂
I. Die Separation Method: Wafer Saw
V. Quality Assurance Information

A. Quality Assurance Contacts:
   Don Lipps (Manager, Reliability Engineering)
   Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level:
   0.1% for all electrical parameters guaranteed by the Datasheet.
   0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate:
   < 50 ppm

D. Sampling Plan:
   Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ($\lambda$) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$

(Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.4 \times 10^{-9}$$

$$\lambda = 22.4 \text{ F.I.T. (60% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S45 Process results in a FIT Rate of 0.49 @ 25°C and 8.49 @ 55°C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PP46-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.
<table>
<thead>
<tr>
<th>TEST ITEM</th>
<th>TEST CONDITION</th>
<th>FAILURE IDENTIFICATION</th>
<th>SAMPLE SIZE</th>
<th>NUMBER OF FAILURES</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Static Life Test</strong> (Note 1)</td>
<td>Ta = 135°C Biased Time = 192 hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>48</td>
<td>0</td>
</tr>
<tr>
<td><strong>Moisture Testing</strong> (Note 2)</td>
<td>Ta = 130°C RH = 85% Biased Time = 96hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td><strong>Mechanical Stress</strong> (Note 2)</td>
<td>Temperature Cycle</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td></td>
<td>-65°C/150°C 1000 Cycles Method 1010</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data